

PAUL SCHERRER INSTITUT



Swiss Accelerator  
Research and  
Technology



Michael Daly :: Paul Scherrer Institute, in collaboration with EMPA Dübendorf and UTwente

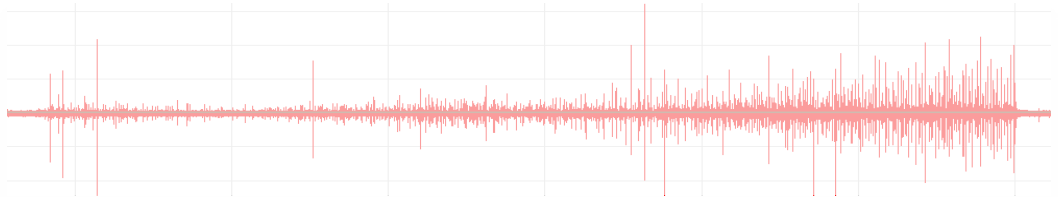
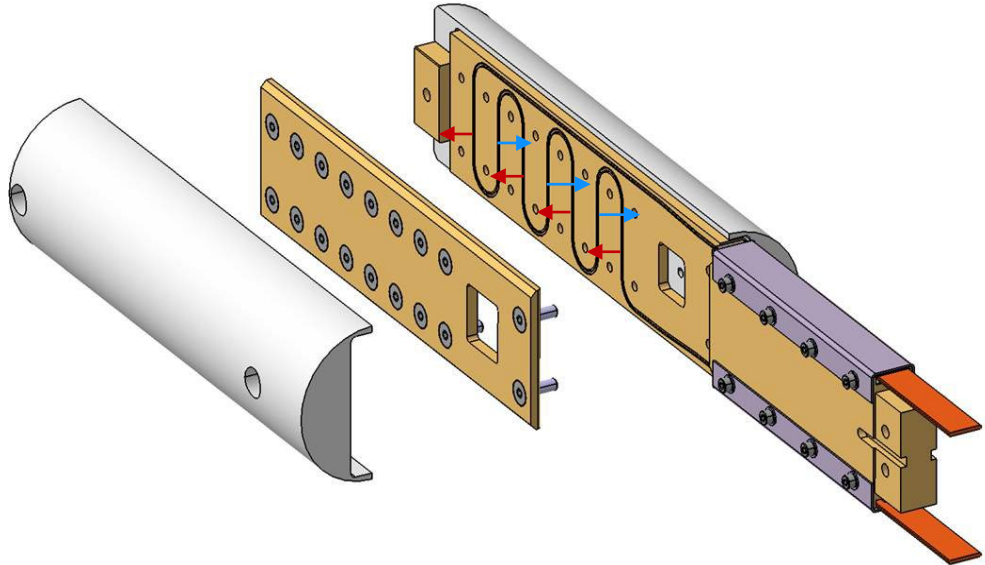
# Using acoustic signals with post-mortem analysis for material research & development

4<sup>th</sup> IDSM workshop 2023 - Paestum, Italy

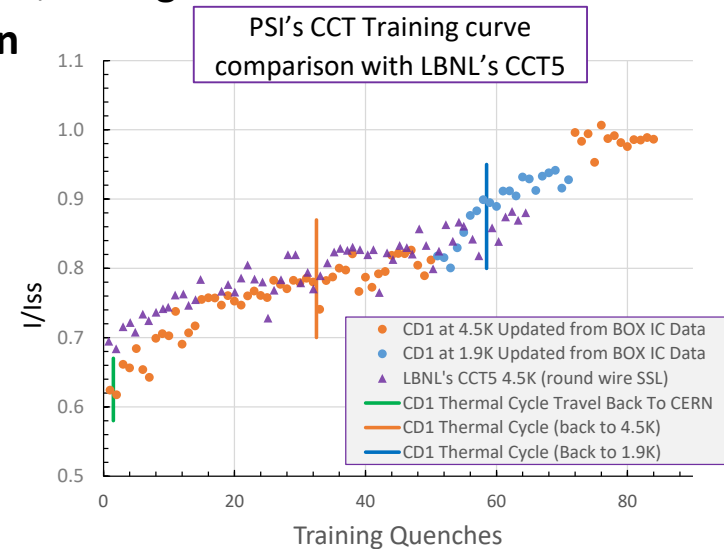
Work supported by the Swiss State Secretariat for Education, Research and Innovation SERI.

Acknowledgements to USMDP and LBNL for supplying the Nb<sub>3</sub>Sn cable

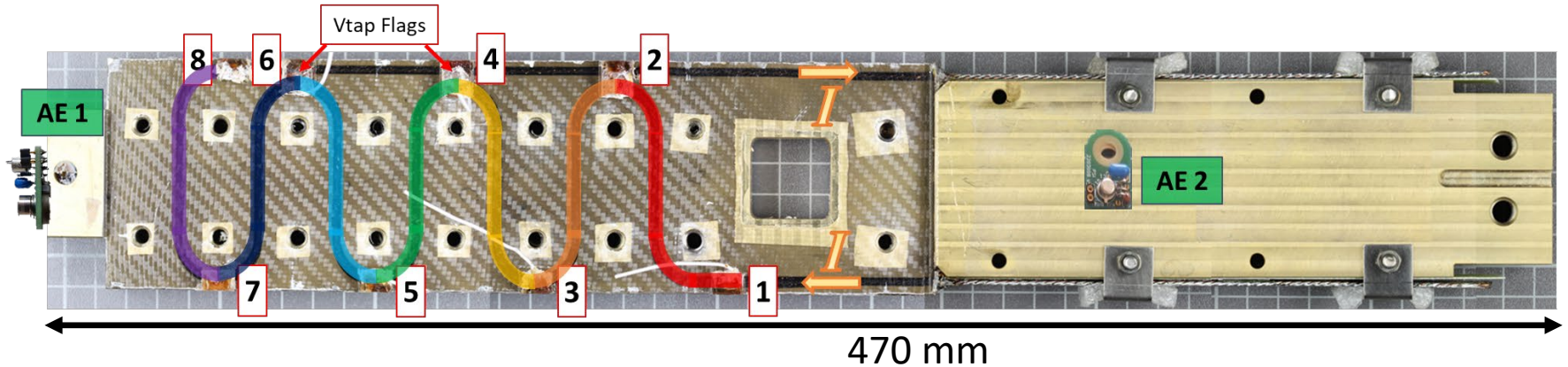
- Context of work
- Experimental details
- Experimental results:
  - Post-mortem analysis
  - AE signals:
    - 1Mhz
    - 100kHz
- Concluding remarks



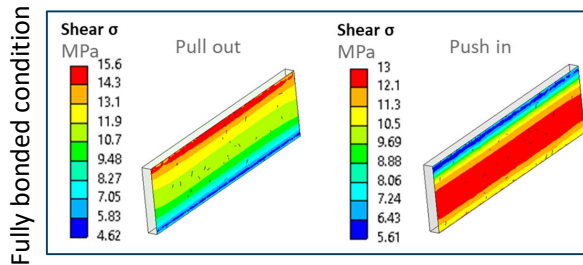
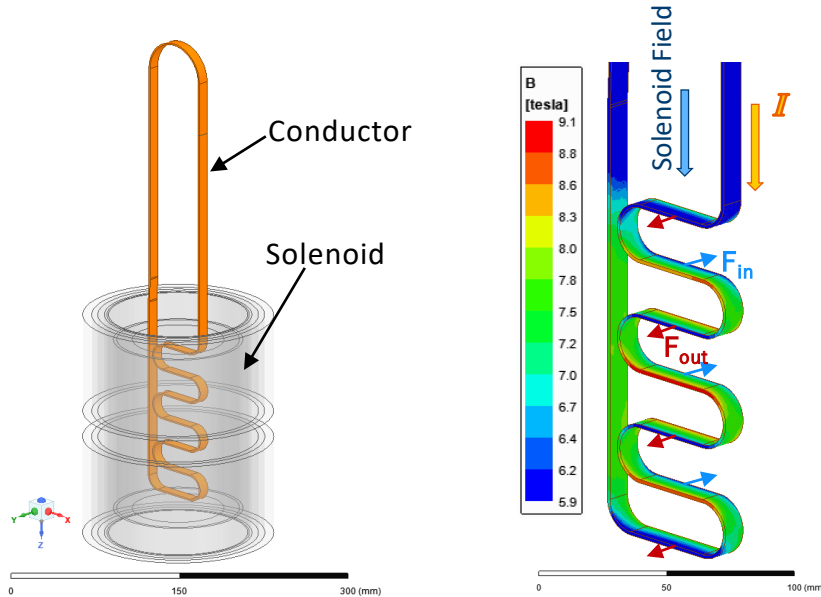
- **Reproduce conductor behaviour in High Field Magnets ( $\text{Nb}_3\text{Sn}$ ,  $\text{NbTi}$ ):**
  - High forces in strong magnetic field (7.5 T to 11 T) at 4.2 K and high currents
  - Failure modes: cracking, debonding, stick slip-motion, sliding
- **... to reduce magnet training and operational limitation**
  - Training quenches
  - Fatigue (cyclic and thermal)
  - Operational stability
- **Requirements:**
  - Cost-effective (actual cost: 5k – 15k€ /test)
  - Fast turn-around (4 - 8 weeks)
  - Reproducible
  - **Assess various fabrication methods, tooling, materials and instrumentation**
  - Improve our understanding by “simplifying” behaviour



- **B**onding **e**xperiment **S**amples (**U**Twente: 7.5 T solenoidal field at 4.2 K)
  - Conductor (Nb<sub>3</sub>Sn: QXF 0.85mm RRP 108/127, 21 strand cable)
  - Aluminium bronze or Stainless steel former
  - Undergoes required heat treatment (max 665 C) and impregnation
  - Instrumentation:
    - Vtaps at each bend and on leads, x2 Acoustic Sensors, and current monitoring
    - Targeted NDE and destructive analysis

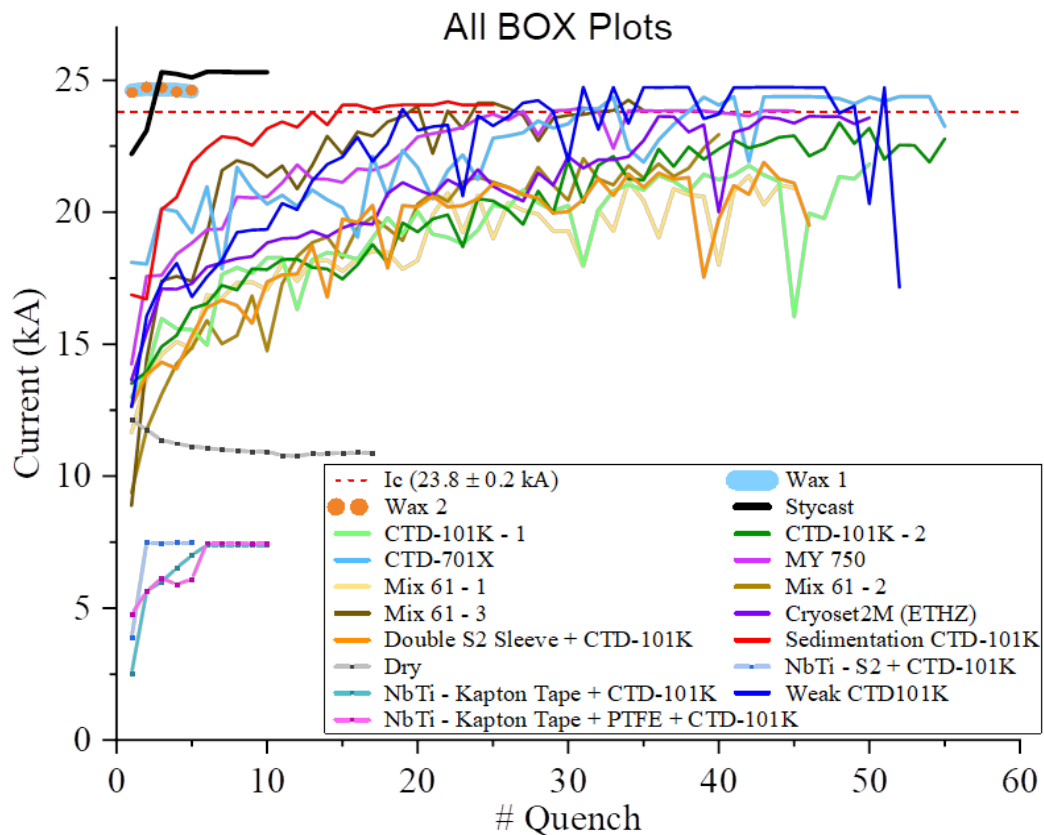


# BOX Samples Results



ID	Identifying feature	Conductor
BOX 1	Mix 61 with Mica	Nb <sub>3</sub> Sn
BOX 2	Mix 61 - Rep CD1 mag	Nb <sub>3</sub> Sn
BOX 3	Mix 61 Rep CD1 improved adhesion	Nb <sub>3</sub> Sn
BOX 4	Non-impregnated	Nb <sub>3</sub> Sn
BOX 5	“Kirby”/CERN CCT (“RED”)	Nb-Ti
BOX 6	Paraffin Wax 1	Nb <sub>3</sub> Sn
BOX 7	CERN CCT Kapton ONLY (“PURPLE”)	Nb-Ti
BOX 8	MY750 (Baseline)	Nb <sub>3</sub> Sn
BOX 9	Paraffin Wax 2	Nb <sub>3</sub> Sn
BOX 10	CTD-701X	Nb <sub>3</sub> Sn
BOX 11	CTD-101K (baseline)	Nb <sub>3</sub> Sn
BOX 12	CTD-101K no 2 (Reproducibility)	Nb <sub>3</sub> Sn
BOX 13	Teflon Coating “BLACK”	Nb-Ti
BOX 14	Ceramic Coating Stycast (Failed)	Nb <sub>3</sub> Sn
BOX 15	Weakened CTD-101K	Nb <sub>3</sub> Sn
BOX 16	Ceramic Coating Stycast	Nb <sub>3</sub> Sn
BOX 17	Sedimented Particles with CTD-101K	Nb <sub>3</sub> Sn
BOX 18	Double fibre glass with CTD-101K	Nb <sub>3</sub> Sn
BOX 19	Higher toughness CryoSet2M	Nb <sub>3</sub> Sn
COMP 1	Paraffin Wax 1	Nb <sub>3</sub> Sn
COMP 2	Paraffin Wax 2	Nb <sub>3</sub> Sn
COMP 3	CTD-101K - 01	Nb <sub>3</sub> Sn
COMP 4	CTD-101K - 02	Nb <sub>3</sub> Sn
COMP 5	Paraffin Wax (Improved filling)	Nb <sub>3</sub> Sn

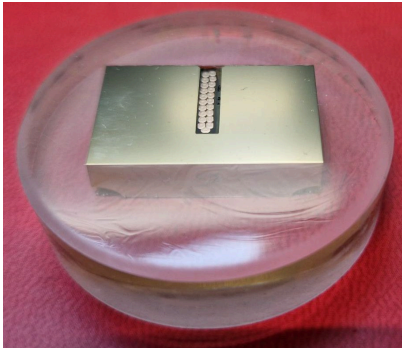
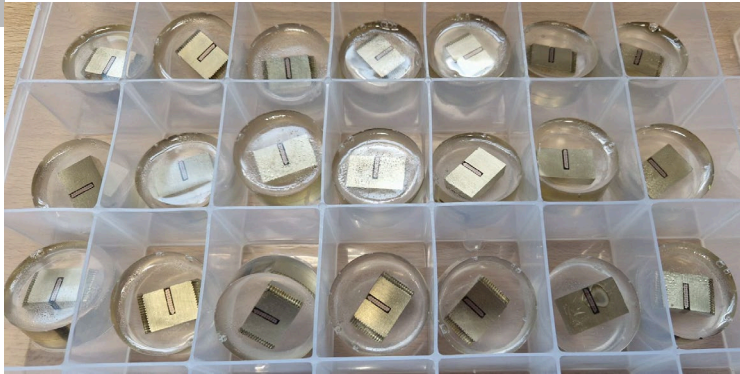
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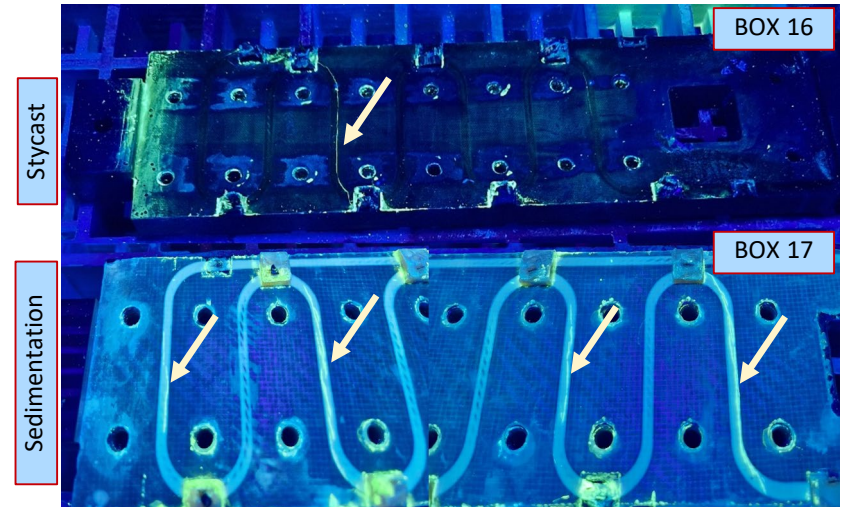


## Destructive

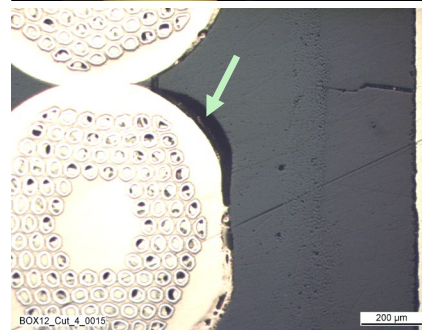
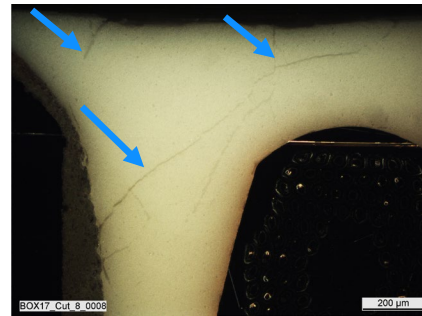
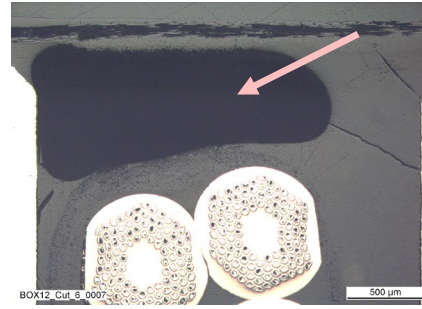
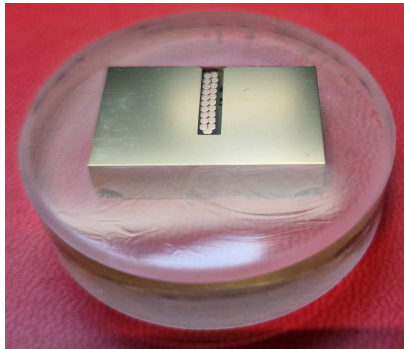
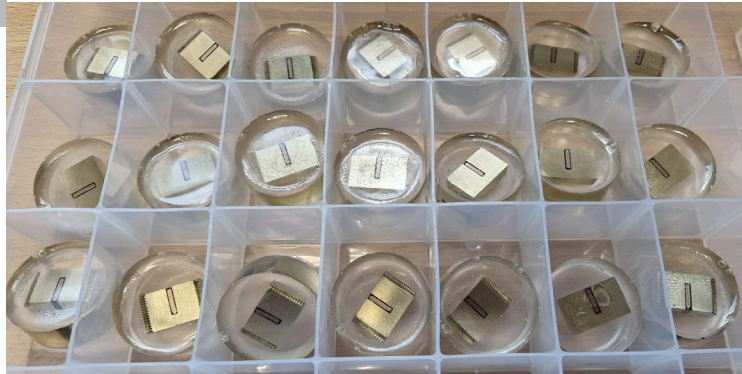


## Non-Destructive

- Face imaging pre- and post-testing
- Dye penetrant on surface
  - Fluorescent and red dye



## Defect characterization

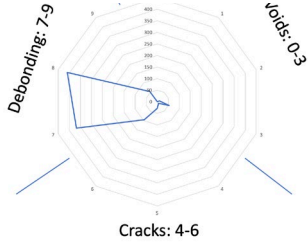


ID	Defect Type
0	Crack $a > 2500 \mu\text{m}$
1	$1500 \mu\text{m} < a < 2500 \mu\text{m}$
2	$250 \mu\text{m} < a < 1500 \mu\text{m}$
3	$a < 250 \mu\text{m}$
4	Void $> 500 \mu\text{m}$
5	$150 \mu\text{m} < \text{Void} < 500 \mu\text{m}$
6	Void $< 150 \mu\text{m}$
7	Crack-like gap w/ Wire
8	Void-like gap w/ Wire
9	Wall Debonding

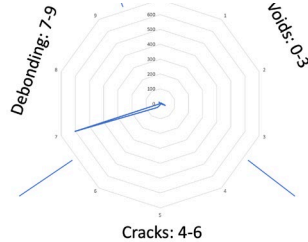


# BOX sample “Fingerprinting”

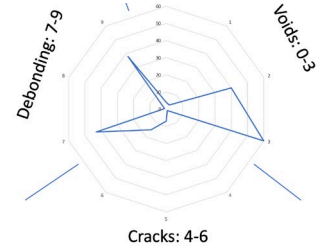
Mix61



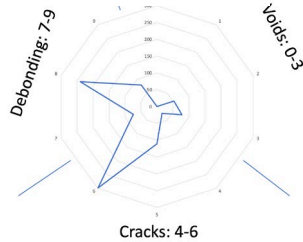
MY 750



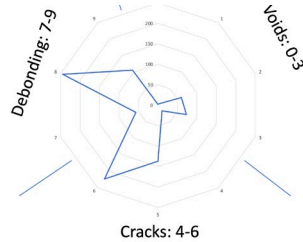
CTD701X



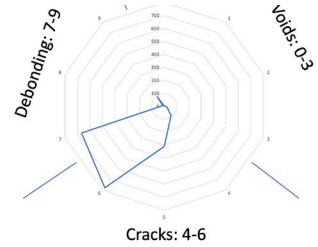
CTD101K - 1



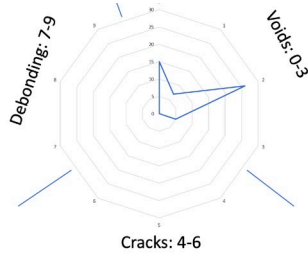
CTD101K - 2



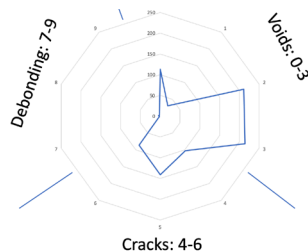
Weak CTD101K



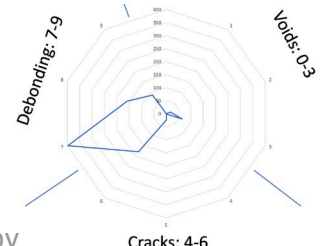
Stycast



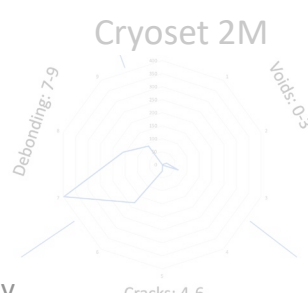
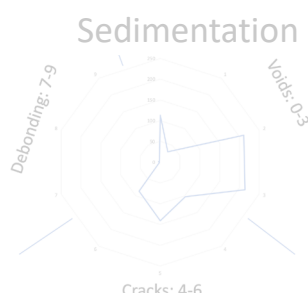
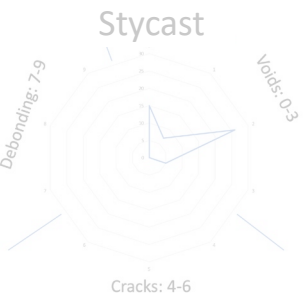
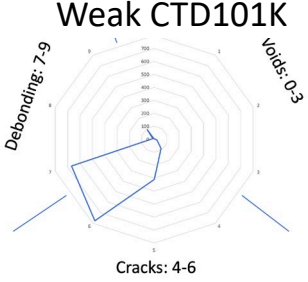
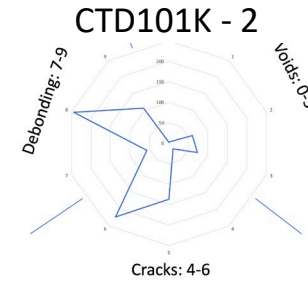
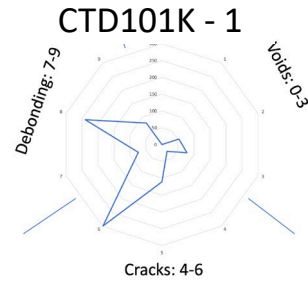
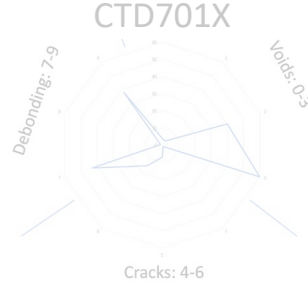
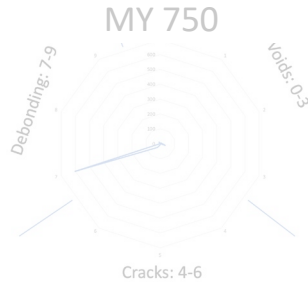
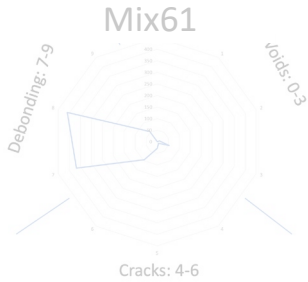
Sedimentation



Cryoset 2M

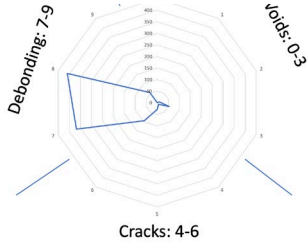


# BOX sample CTD-101 K Series

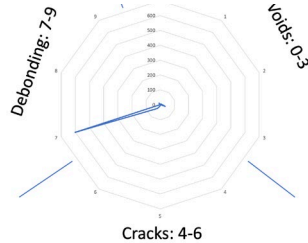


# BOX sample "Tough" Resin Series

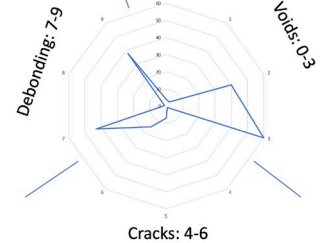
Mix61



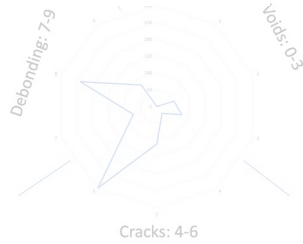
MY 750



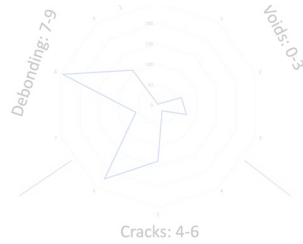
CTD701X



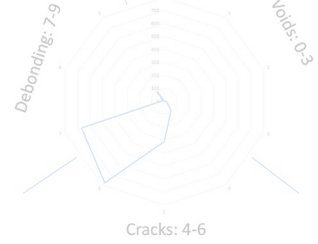
CTD101K - 1



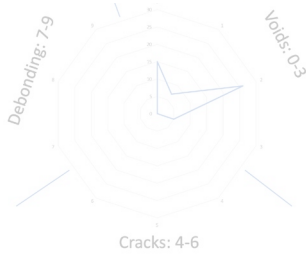
CTD101K - 2



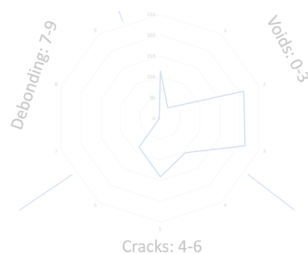
Weak CTD101K



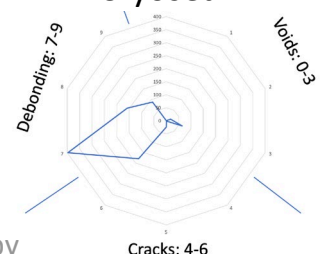
Stycast



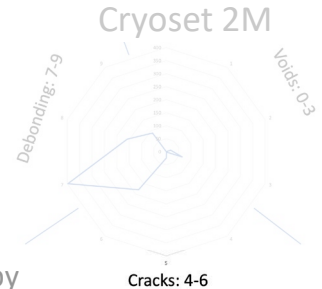
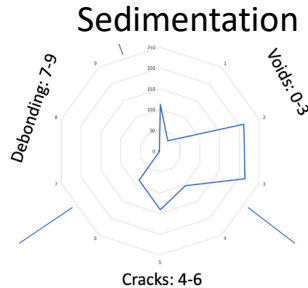
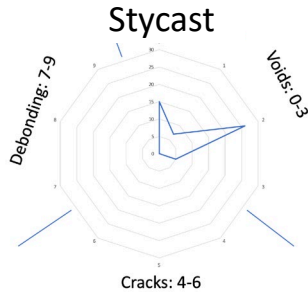
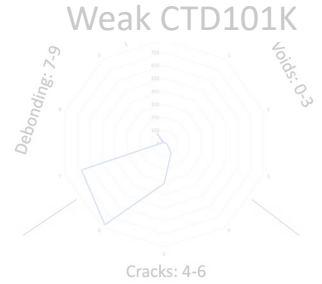
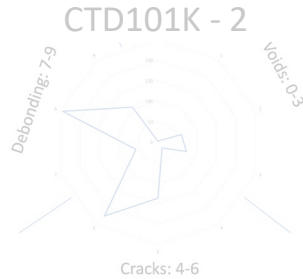
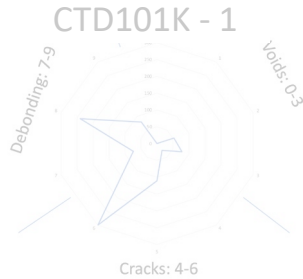
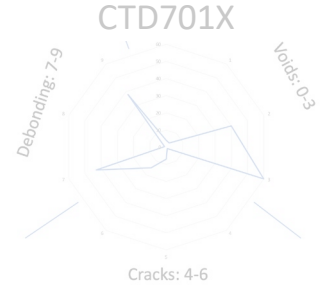
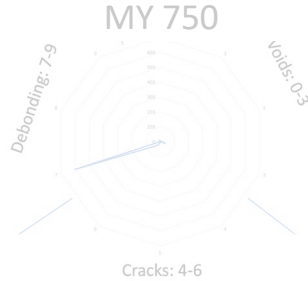
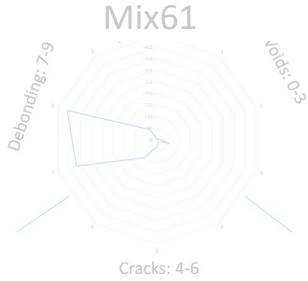
Sedimentation



Cryoset 2M



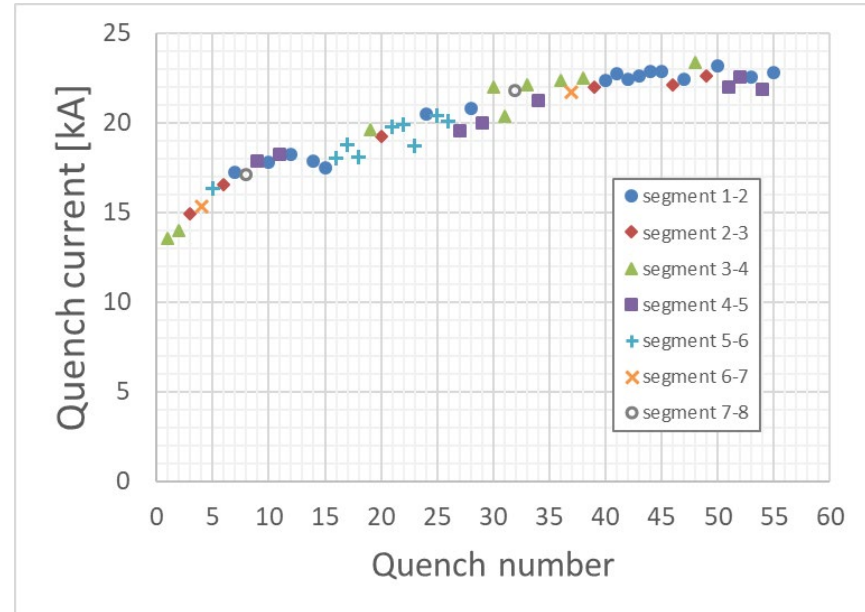
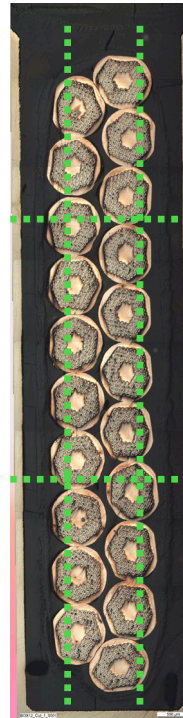
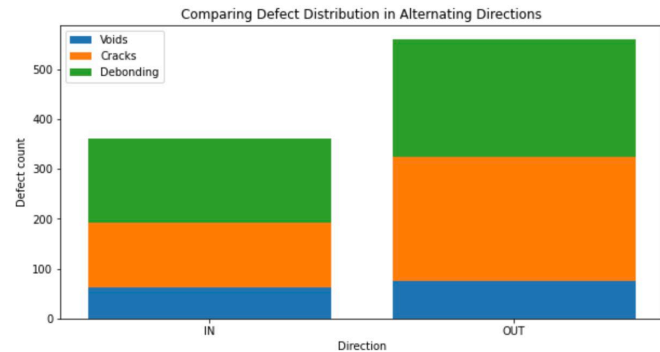
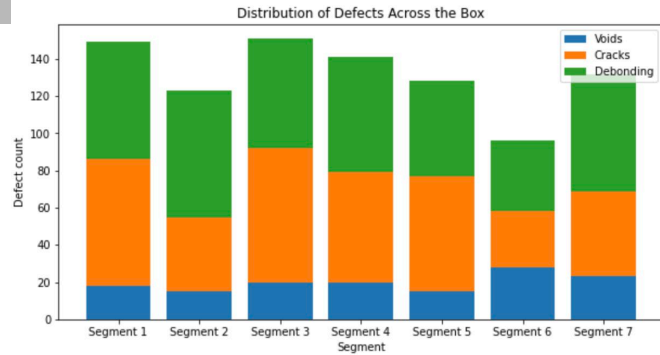
# BOX sample Filled Systems Series



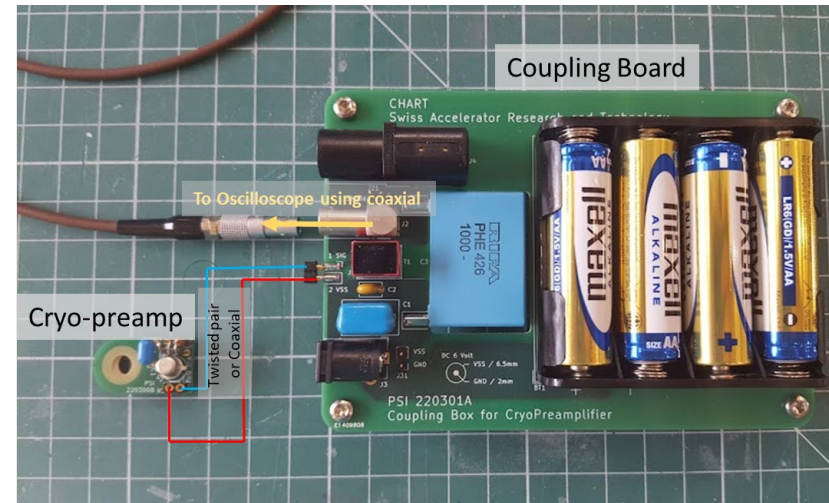


# Single BOX data summary

- Post-mortem data specific to each BOX and each segment with location of defects and knowledge of quench segment.

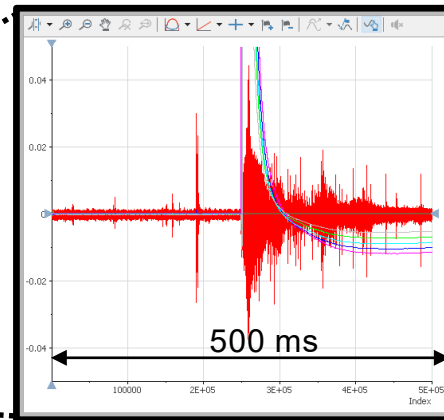
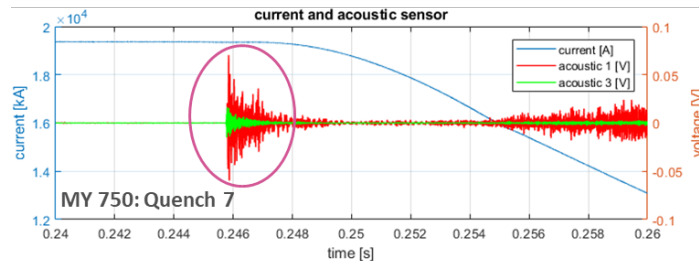
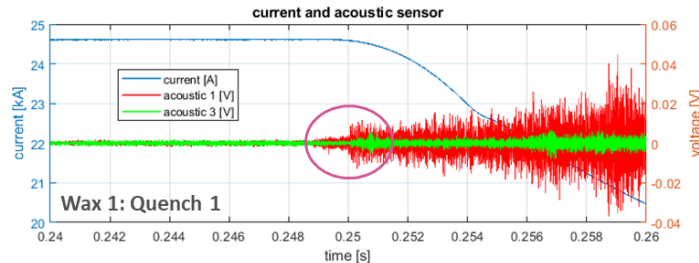
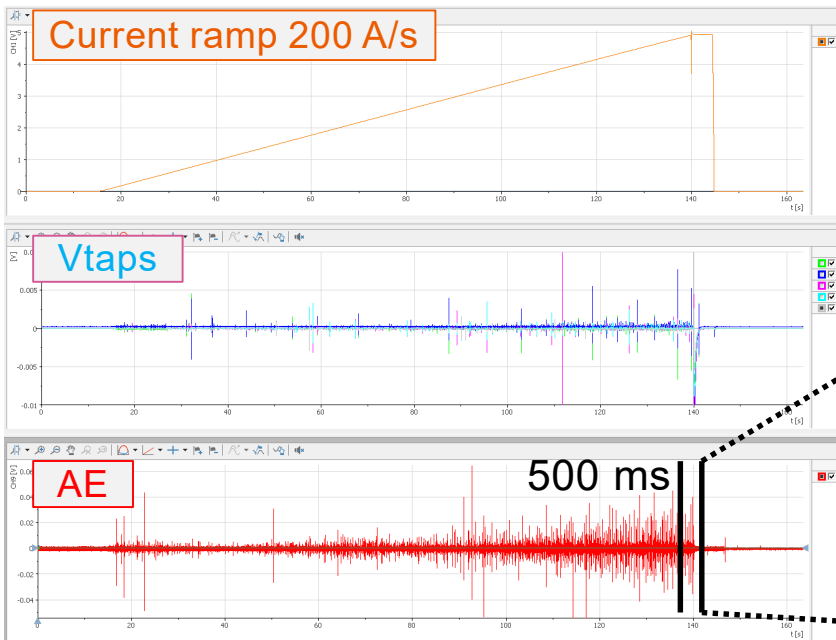


- **Aims:**
  - **Help assess BOXs as an R&D device (Failure analysis: Cracking, debonding, stick-slip)**
  - **To use as a monitoring and diagnostic device for magnets.**
- Design based on LBNL's Maxim Marchevsky's design
  - MOSFET (3N163) and Piezo rings purchased from Supplier in USA
- Screwed unto BOX using stainless steel screw
- Spring washer and copper washer interface with BOX
- Data recorded on Yokogawa DL850EV oscilloscope:
  - Full ramp approx. 2mins
  - Full ramp recorded at **100 kHz**
  - 250 ms before and after quench recorded at **1 MHz**



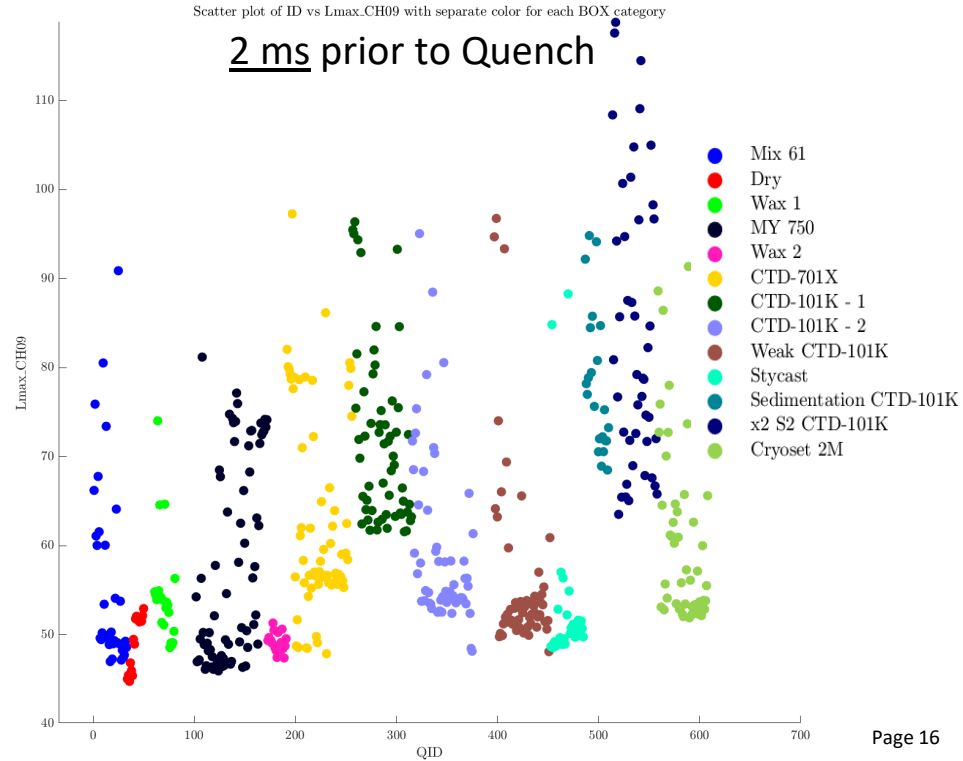
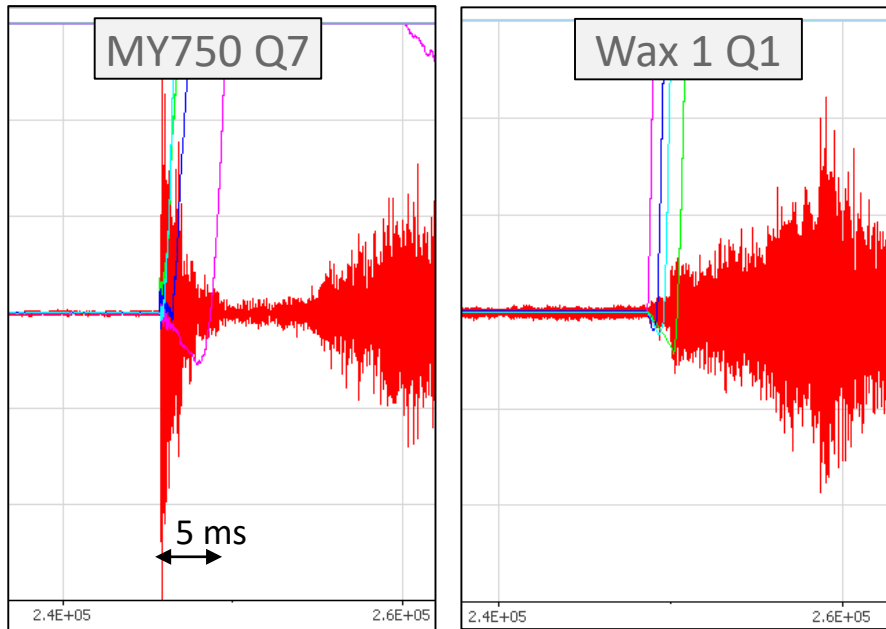
# AE Acquired Data

- 1 MHz data  $\approx$  24MB; 100 kHz data  $\approx$  400MB
- 608 Quenches (QIDs)
- >1000 ramps (incl cyclic ramps)
- 360 GB of raw data



# “Expectations vs Reality” (1 MHz data)

- Does an acoustic event precede or proceed a quench?
  - Did a crack or movement release sufficient energy to quench ?



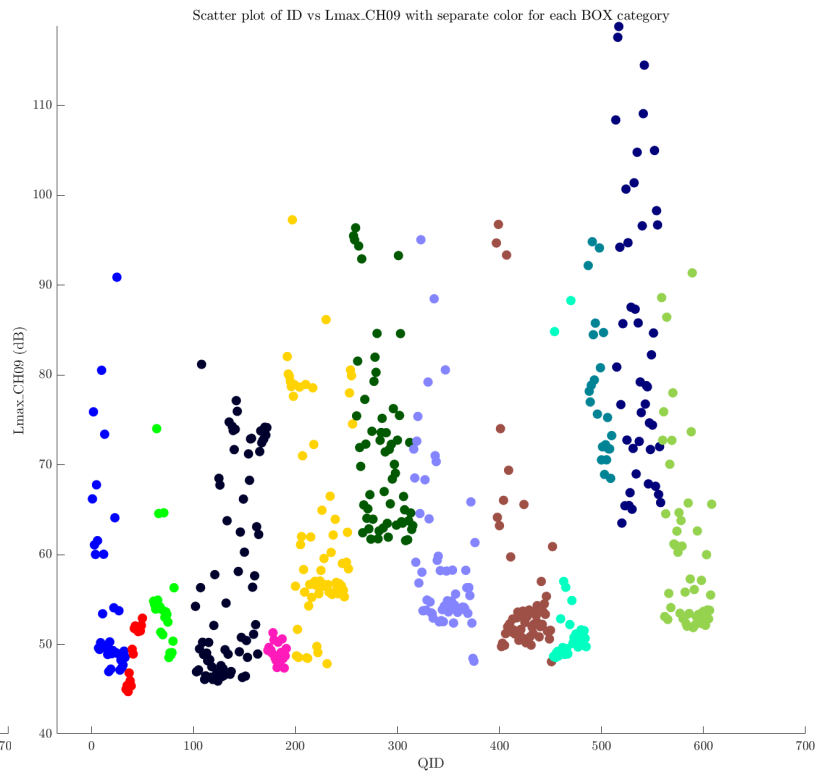
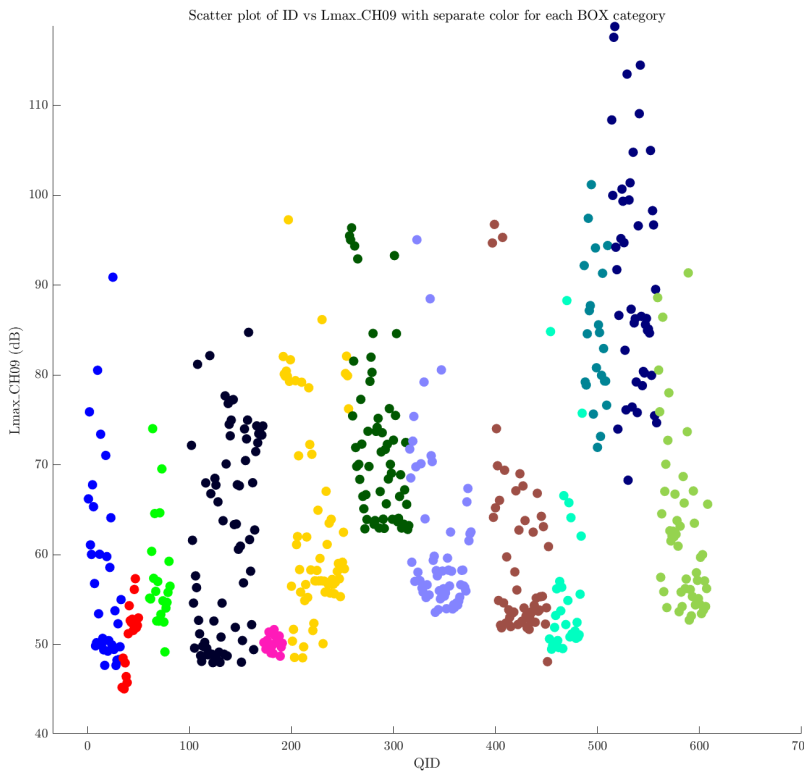


# “Expectations vs Reality” (1 MHz data)

20 ms prior to Quench

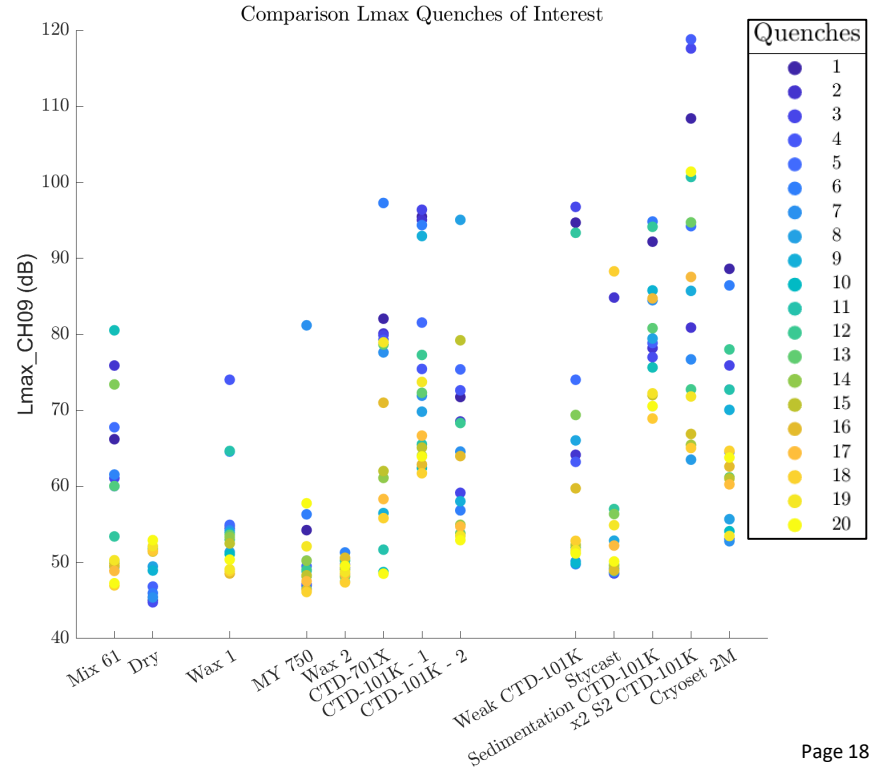
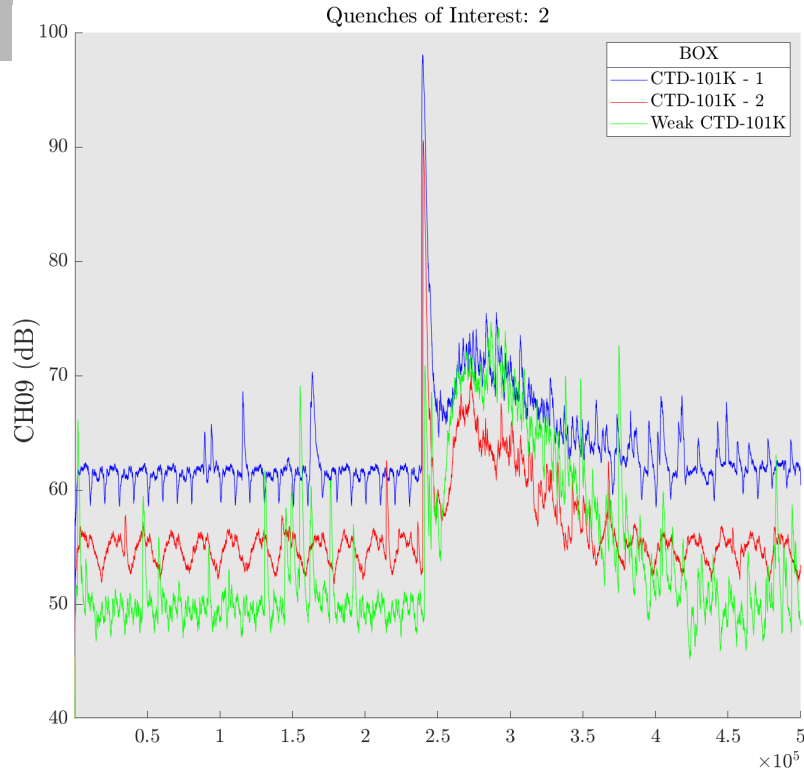
2 ms prior to Quench

- Mix 61
- Dry
- Wax 1
- MY 750
- Wax 2
- CTD-701X
- CTD-101K - 1
- CTD-101K - 2
- Weak CTD-101K
- Stycast
- Sedimentation CTD-101K
- x2 S2 CTD-101K
- Cryoset 2M



# Energy levels Comparisons (1 MHz data)

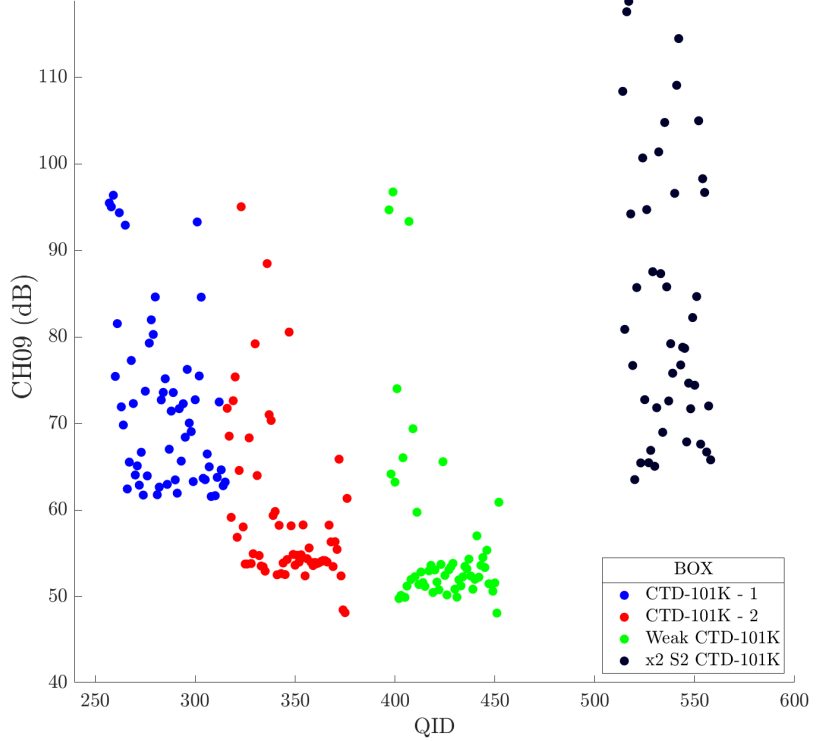
- Earlier events seem more energetic than later events.
- Background noise artificially increases energy levels



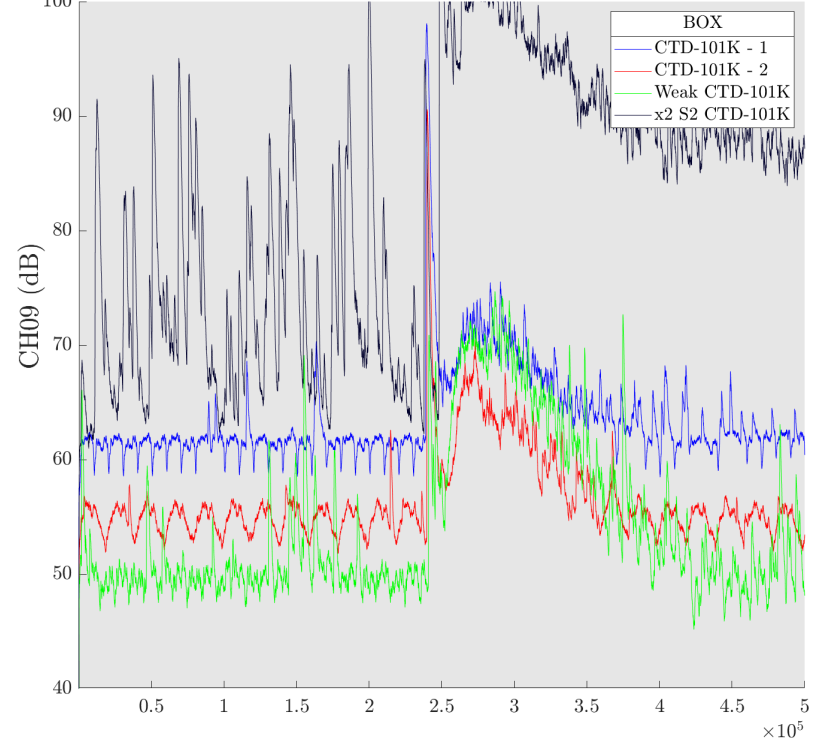
# Energy levels Comparisons (1 MHz data)

- In some cases, piezo sensors pick up excess background noise (increased sensitivity).
- Filters and offsets cannot always compensate.

Scatter plot of ID vs Lmax.CH09 with separate color for each BOX category

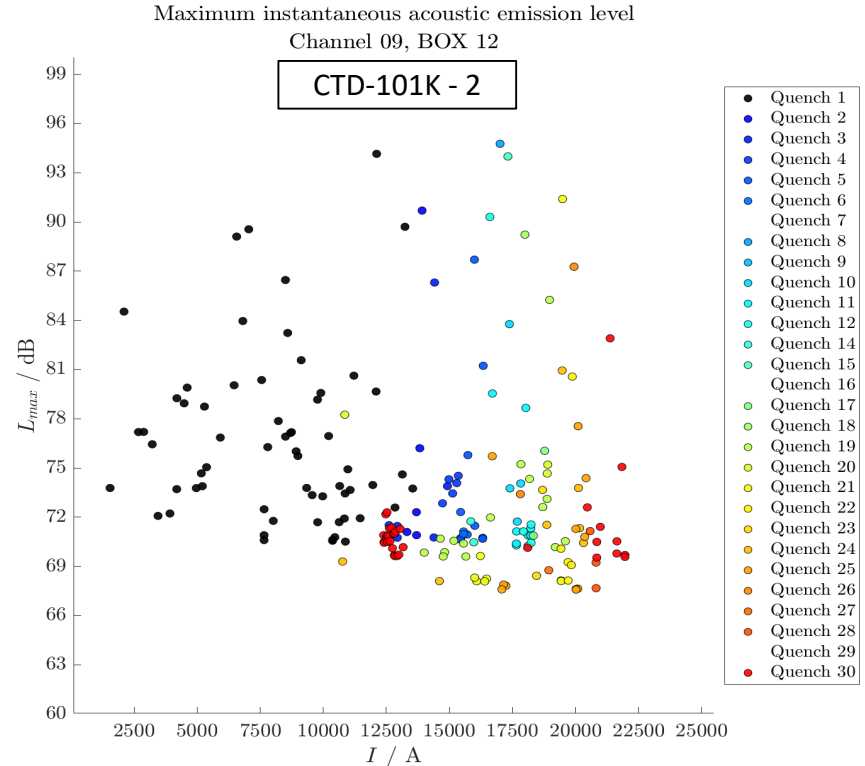


Quenches of Interest: 2



# Energy levels Comparisons (100 kHz data)

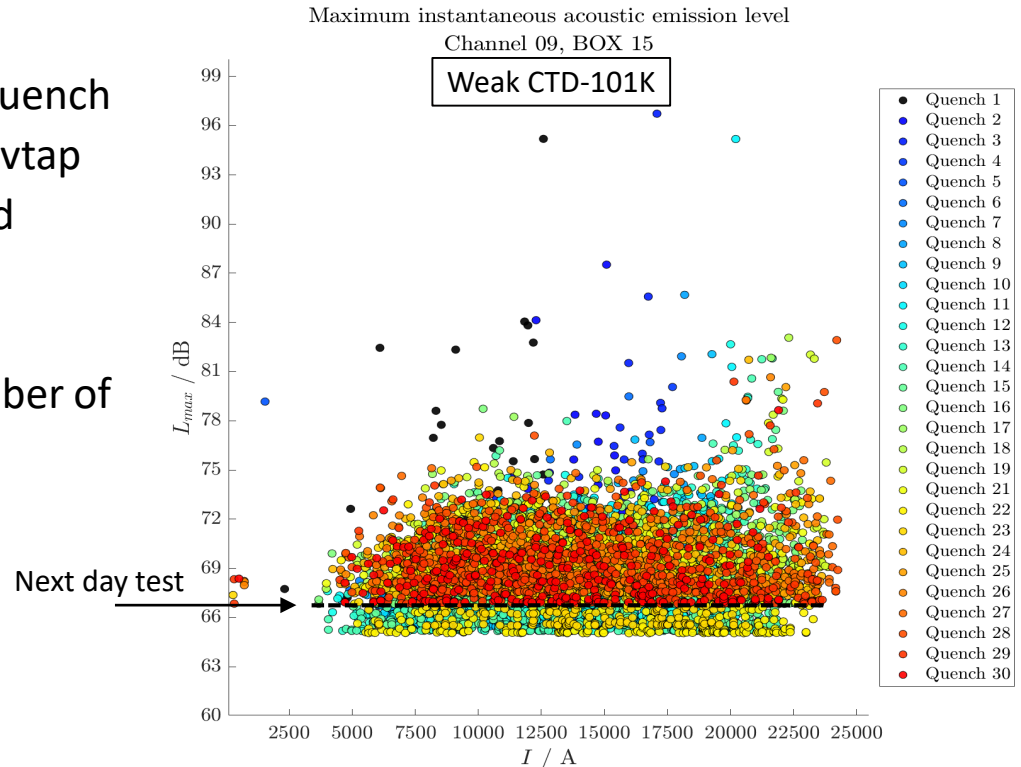
- Energy levels for 100 kHz:
  - Captures the complete ramp to quench
- Uses a combination of AE data and vtap data to determine T0 of quench and thresholds
  - Threshold is specific to sample
- Scattered Results depend on a number of parameters:
  - Filters
  - Threshold
  - Offset
  - And, piezo sensitivity





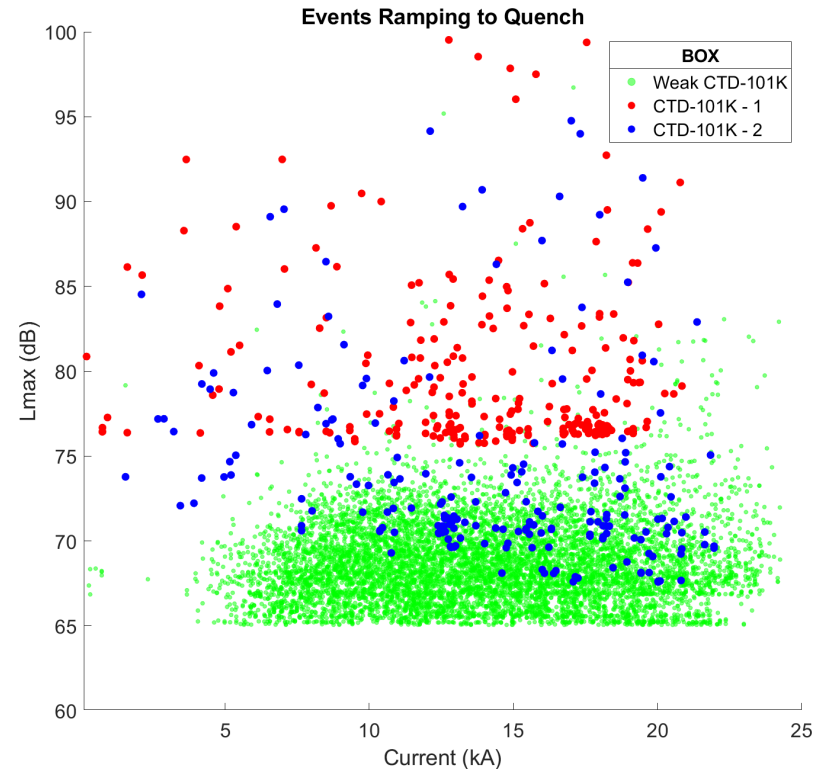
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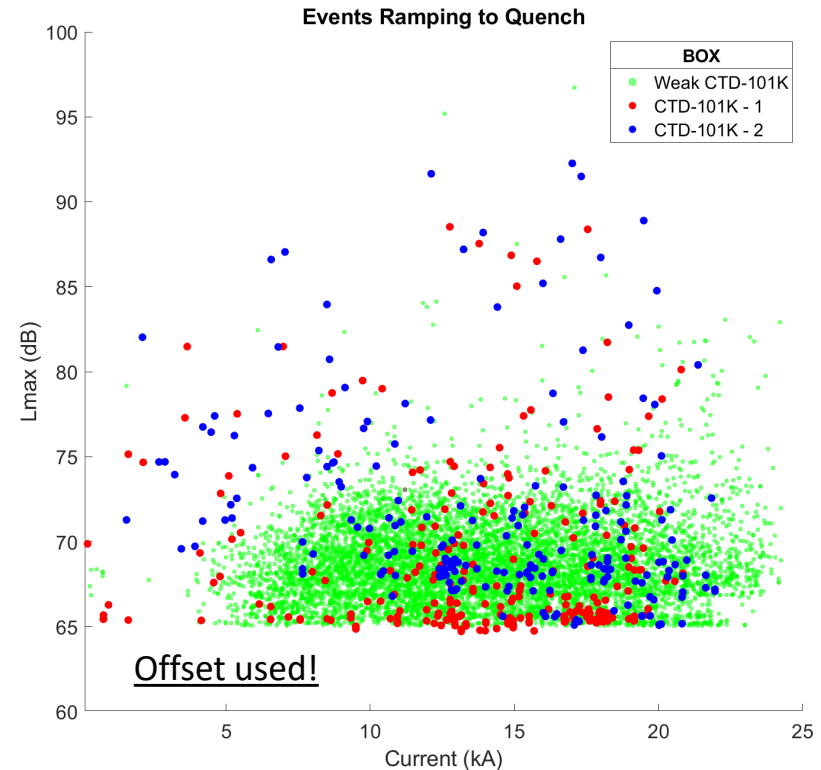
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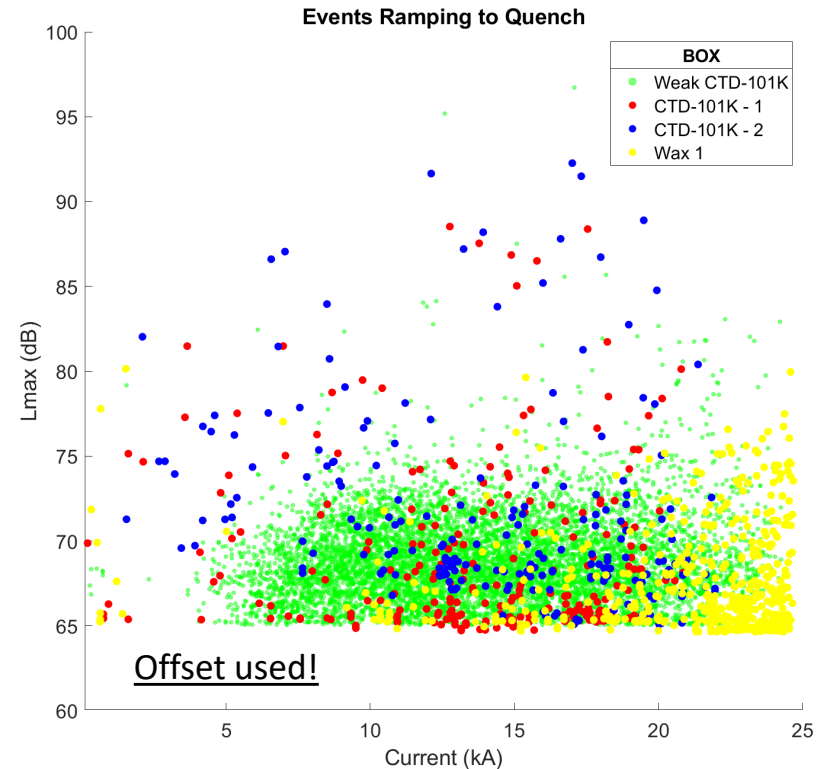
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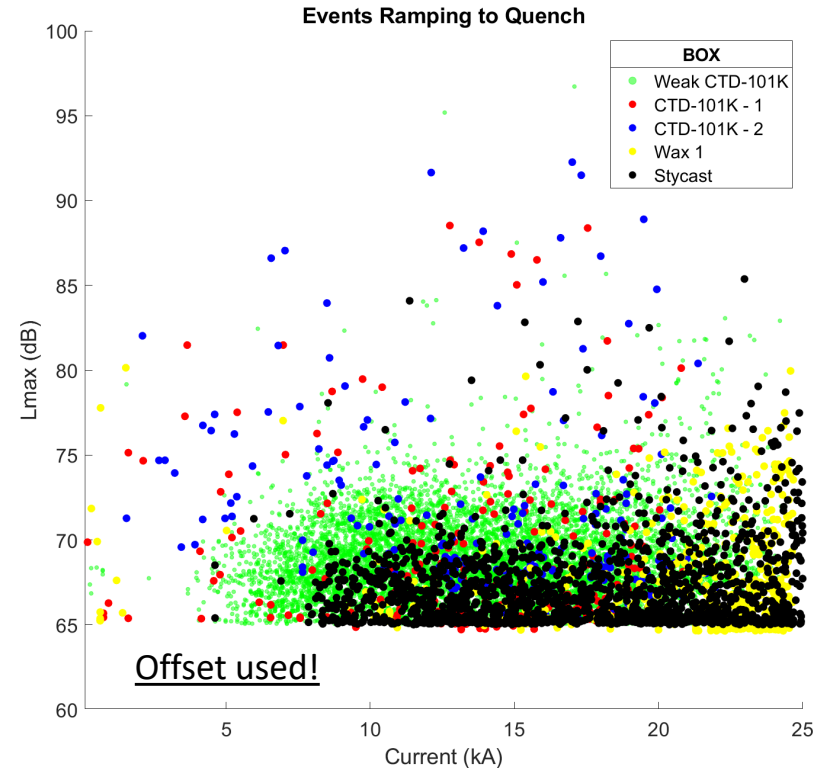
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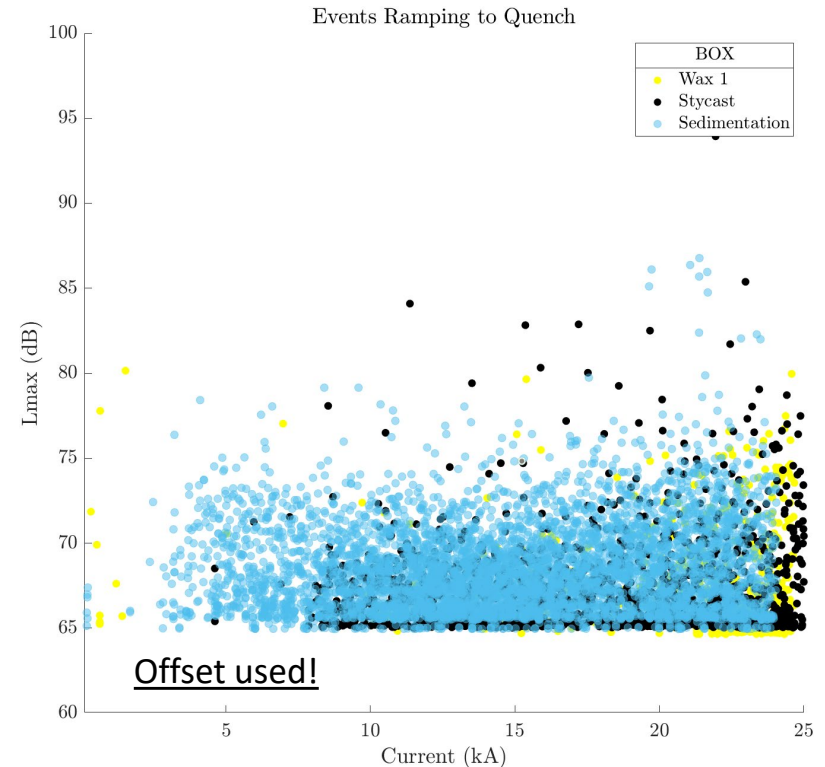
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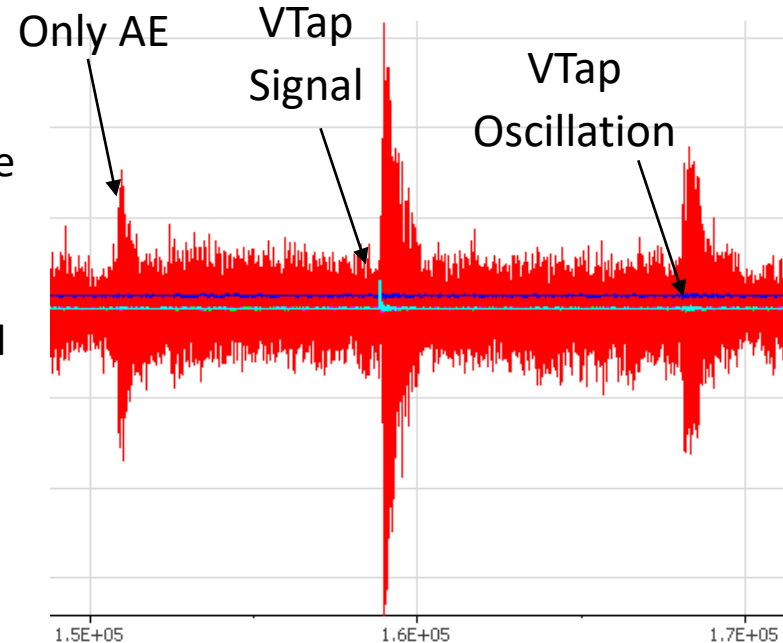


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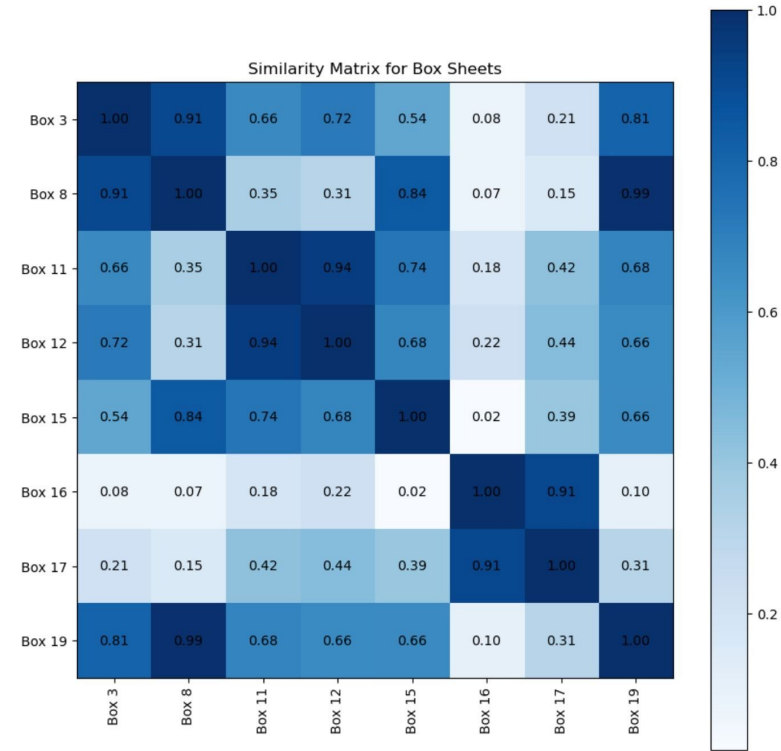


- More refined Analysis (Code improvements)
  - Adaptive thresholds
  - How to use both AE 1 and AE 2 to compensate
- Detection:
  - Do we have vtap signals with AE events?
- Correlate with experimental conditions & material properties:
  - Forces at quenching currents
  - MQE evaluation
  - Observed defects
  - Material Properties (CTE,  $K_{IC}$ ...)
- Wavelet analysis
  - Early events and precursors
- In-situ calibration with inducers/waveform generator



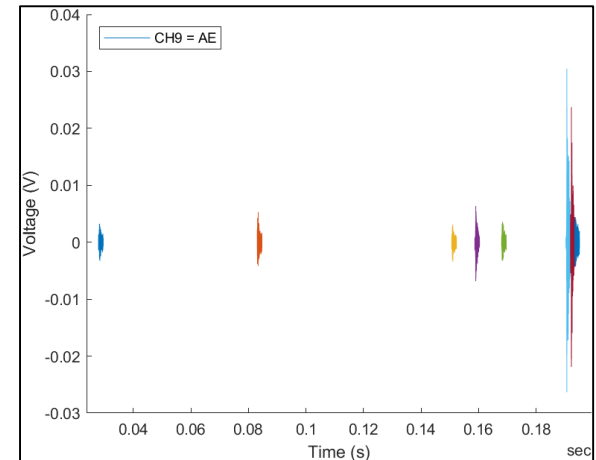
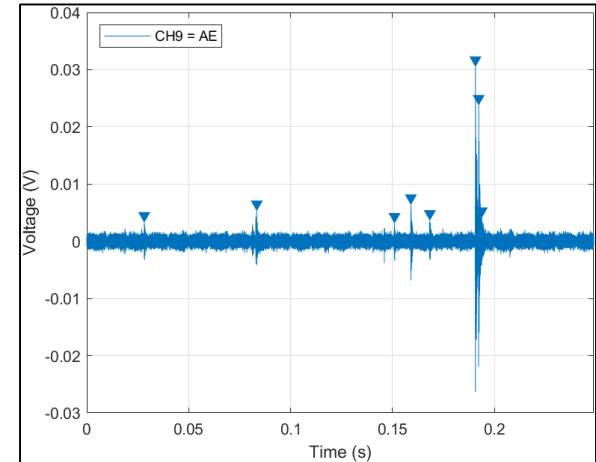


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Courtesy of Oliver. Kirby

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# Concluding remarks

- BOX is used to benchmark and assess:
  - Materials (resins, fillers, wax), coatings and processes
- Acoustic Sensors can complement diagnostics and analysis of samples
  - Energy levels:
    - Some Quenches show clear precursors
  - Noise of samples
    - Some indication that noise levels and quantity of events correlate to performance of BOXs
- Some correlation possible with post-mortem analysis and material properties.
- Nevertheless, further work required to better differentiate between acoustic phenomena (normalising, offsets thresholding).

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